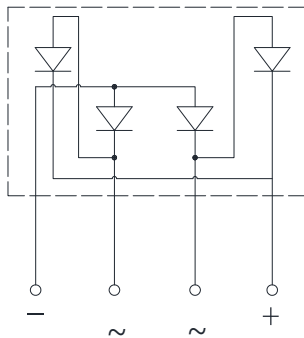
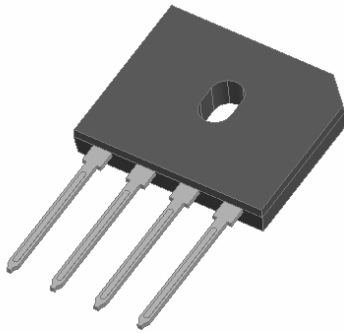


Low VF Bridge Rectifiers



Features

- UL recognition, file #E230084
- based on silicon planar process
- Ideal for printed circuit boards
- High surge current capability
- Low VF
- Solder dip 275 °C max. 7 s, per JESD 22-B106

Typical Applications

General purpose use in AC/DC bridge full wave Rectification for monitor, TV, printer, power supply, switching mode power supply, adapter, audio equipment, and home appliances applications.

Mechanical Data

- **Package:** GBU
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** As marked on body

■Maximum Ratings (T_a=25 °C Unless otherwise specified)

PARAMETER		SYMBOL	UNIT	GBUU1506
Device marking code				GBUU1506
Maximum Repetitive Peak Reverse Voltage		V _{RRM}	V	600
Maximum RMS Voltage		V _{RMS}	V	420
Maximum DC blocking Voltage		V _{DC}	V	600
Average rectified output current @60Hz sine wave, R-load	With heatsink T _c =110 °C	I _O	A	15.0
	Without heatsink T _a =25 °C			3.5

Forward Surge Current I_{FSM} (Non-repetitive) (Non-² V)

Current squared time @1ms≤t≤8.3ms T _j =25 °C, Rating of per diode		I ² t	A ² S	200.9
Storage temperature		T _{stg}		-55 ~ +150
Junction temperature		T _j		-55 ~ +150
Dielectric strength @ terminals to case, AC 1 minute		V _{dis}	KV	2.5
Mounting torque @recommend torque 5kg cm		T _{or}	kg cm	8.0



GBUU1506

■Electrical Characteristics $T_a=25$ Unless otherwise specified

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	Min	Typ	Max
Instantaneous forward voltage drop per diode	V_F	V	$I_{FM}=7.5A$	0.80	0.88	0.92
DC reverse current at rated DC blocking voltage per diode	I_R	μA	$T_j=25$	-	0.08	5
			$T_j=125$	-	2.5	50
Junction capacitance	C_j	pF	Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	64	128	250

■Thermal Characteristics $T_a=25$ Unless otherwise specified

PARAMETER		SYMBOL	UNIT	GBUU1506
Thermal Resistance	Between junction and ambient, Without heatsink	$R_{\theta J-A}$	/W	25.0
	Between junction and case, With heatsink	$R_{\theta J-C}$		1.4
	Between junction and Lead With heatsink	$R_{\theta J-L}$		5



■ Outline Dimensions

GBU		
Dim	Min	Max
A	21.80	22.30
B	18.30	18.80
C	17.50	18.00
D	3.30	3.90
E	7.10	7.50
F	5.50	5.90
G	1.91	2.54
H	2.06	2.54



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